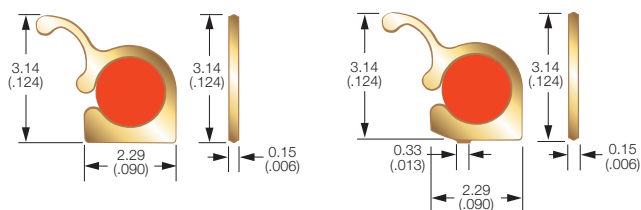


0.4MM DYNO CONTACT

RP DYNO CONTACT



SPECIFICATIONS

Minimum Device Pitch: 0.40mm (.016)
Test Height: 2.92mm (.115)
Force per Contact:
42g (1.5 oz.) @ 0.38mm (.015) travel for RP
55g (1.9 oz.) @ 0.38mm (.015) travel
Device Compliance: 0.23mm (.009)
DUT Board Compliance: 0.15mm (.006)
Operating Temperature: -55°C to 150°C
Insertions: > 500,000

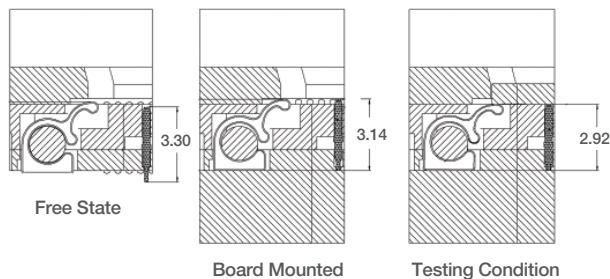
MATERIALS

Contact: Full-hard beryllium copper, Endura plated
Insulator: Silicone

ELECTRICAL SPECIFICATIONS

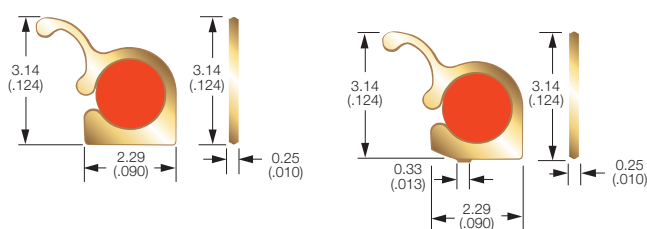
Typical Resistance: < 20 mΩ
Current Carrying Capacity: 5 amps continuous
(Current DC carry capability @ 80° C steady state)
Pattern 2a: R S R at 0.4mm pitch
Characteristic Impedance: 34 Ω
Time Delay: 37 pSec
Loop Inductance: 1.51 nH
Signal Pin to Return Capacitance: 0.90 pF
-1dB Insertion Loss Bandwidth: >10 GHz

TESTING CONDITION



0.5MM DYNO CONTACT

RP DYNO CONTACT



SPECIFICATIONS

Minimum Device Pitch: 0.50mm (.020)
Test Height: 2.92mm (.115)
Force per Contact:
52g (1.8 oz.) @ 0.38mm (.015) travel for RP
85g (3.0 oz.) @ 0.38mm (.015) travel
Device Compliance: 0.23mm (.009)
DUT Board Compliance: 0.15mm (.006)
Operating Temperature: -55°C to 150°C
Insertions: >500,000

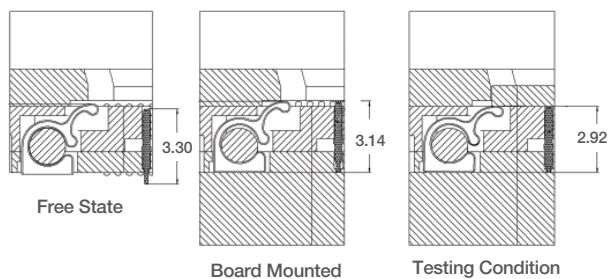
MATERIALS

Contact: Full-hard beryllium copper, Endura plated
Insulator: Silicone

ELECTRICAL SPECIFICATIONS

Typical Resistance: < 20 mΩ
Current Carrying Capacity: 5 amps continuous
(Current DC carry capability @ 80° C steady state)
Pattern 2a: R S R at 0.5mm pitch
Characteristic Impedance: 34 Ω
Time Delay: 48 pSec
Loop Inductance: 1.74 nH
Signal Pin to Return Capacitance: 1.34 pF
-1dB Insertion Loss Bandwidth: >10 GHz

TESTING CONDITION



Specifications subject to change without notice. Dimensions in millimeters (inches)